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Sir:

Transmitted herewith for filing is the patent application of

Inventors: MASANORI TAKAHASHI ET AL.

For: DRIVE CIRCUIT CONNECTION STRUCTURE AND DISPLAY APPARATUS
INCLUDING THE CONNECTION STRUCTURE

Enclosed are:

Specification and Claims.

Oath or Declaration.

Transmittal Letter Under 37 C.F.R. § 1.53 and M.P.E.P. § 601.01.

Seven (7) sheets of formal drawings.

An assignment of the invention to _____

Certified copies of _____ priority application(s).

Associate power of attorney.

The fee has been calculated as shown below:

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Applicants' undersigned attorney may be reached in our New York office by telephone at (212) 758-2400. All correspondence should continue to be directed to our address given below.

Abigail Covins

Attorney for Applicants
Reg. No. 29292

FITZPATRICK, CELLA, HARPER & SCINTO.
277 Park Avenue
New York, New York 10172
Facsimile: (212) 758-2982

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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
MASANORI TAKAHASHI ET AL.)
Application No.: NYA)
Filed: Herewith)
For: DRIVE CIRCUIT CONNECTION)
STRUCTURE AND DISPLAY :
APPARATUS INCLUDING THE)
CONNECTION STRUCTURE : March 7, 1997

Assistant Commissioner for Patents
Washington, D.C. 20231

TRANSMITTAL LETTER UNDER 37 C.F.R. § 1.53
AND M.P.E.P. § 601.01

Sir:

Enclosed herewith for filing is a specification
under 37 C.F.R. § 1.71; claims under 37 C.F.R. § 1.75; and
drawings under 37 C.F.R. § 1.81 for a patent application for
DRIVE CIRCUIT CONNECTION STRUCTURE AND DISPLAY APPARATUS
INCLUDING THE CONNECTION STRUCTURE on behalf of the inventors
under 37 C.F.R. § 1.41(c), MASANORI TAKAHASHI, a citizen of
Japan, having a post office address of 2-6-44-101 Tomoe,
Chigasaki-shi, Kanagawa-ken, Japan, RIICHI SAITO, a citizen
of Japan, having a post office address of 34-2-610 Fujisawa,
Fujisawa-shi, Kanagawa-ken, Japan and TOSHIMICHI OUCHI, a
citizen of Japan, having a post office address of 740-29-306
Kudencho, Sakae-ku, Yokohama-shi, Kanagawa-ken, Japan.

Priority is based upon Japanese Patent Application
No. 059665/1996 (Pat.) filed March 15, 1996.

The undersigned is authorized to file the subject
application on behalf of the inventors.

Applicants' undersigned attorney may be reached in
our New York office by telephone at (212) 758-2400. All
correspondence should be directed to our address given below.

Respectfully submitted,

Asian Covens
Attorney for Applicants

Registration No. 29,292

FITZPATRICK, CELLA, HARPER & SCINTO
277 Park Avenue
New York, New York 10172
Facsimile: (212) 758-2982

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DRIVE CIRCUIT CONNECTION STRUCTURE AND
DISPLAY APPARATUS INCLUDING THE CONNECTION STRUCTURE

FIELD OF THE INVENTION AND RELATED ART

5 The present invention relates to a drive circuit connection structure suitable for use in a display apparatus, and particularly a connection structure including a drive semiconductor device connected to a periphery of a transparent substrate of a display panel constituting such a display apparatus and a circuit board connected to the semiconductor device for supplying input signals and a power to the semiconductor device.

15 Hitherto, there have been known display apparatus including flat display devices having display electrodes arranged in the form of, e.g., a matrix, such as EL display panels and liquid crystal display panels of the simple matrix-type and the active matrix-type. Such display apparatus have 20 conventionally included a circuit connection structure including a transparent substrate, such as a glass substrate or a plastic substrate, provided with display electrodes arranged in the form of, e.g., a matrix; a flexible tape carrier package (TCP) loaded 25 with a driver IC by the TAB (tape-automated bonding) method; and a print circuit board (PCB, hereinafter sometimes called "PCB board"), connected in this

order.

Figure 12 and Figure 13 (a view showing an A-A' section in Figure 12) illustrate an example of such a drive circuit connection structure for a flat display panel. Referring to these figures, the connection structure includes TCPs 4ap and 8p loaded with driver ICs (as drive semiconductor circuits) 5p and 9p and copper foil patterns 32 (as output electrodes), glass substrates 1ap and 1bp for a liquid crystal panel 1 having electrode terminals 12p extended to peripheries thereof, and ACFs (anisotropic conductive films or anisotropic conductive adhesive) 31 for heat-bonding the copper foil patterns 32 on the TCPs with the electrode terminals 12p on the glass substrates. Further, PCB boards 3p for supplying a power and control signals to the driver ICs 5p and 9p are connected with copper foil patterns 17 (as input electrodes) of the TCPs 4ap with solder 20p.

In such a display panel connection structure for a display apparatus as shown in Figures 12 and 13, as the display panel (particularly a liquid crystal panel) is provided with a larger number of display electrodes at a higher density, the connection pitch for connection between the output electrodes of the TCPs and the electrode terminals on the transparent substrates are decreased down to a required pitch of 50 μm or smaller. However, according to a method for

connecting TCP with a substrate as explained with reference to Figures 12 and 13, a very sophisticated and accurate bonding technique is required for ensuring such a minute connection pitch because of a 5 limitation in size accuracy of TCPs and a deviation due to thermal expansion during connection by heat bonding of TCPs. Therefore, a connection structure as shown in Figure 14 including bonding of driver ICs 5 to a substrate 1bp by a face-down mode has been 10 proposed or ensuring such a minute connection pitch.

More specifically, referring to Figure 14, the connection structure includes a connection by the face-down bonding mode of driver ICs 5 with electrode terminals extended to peripheries of a pair of glass 15 substrates 1ap and 1bp of a display panel and with input electrodes (not shown) formed on the glass substrates 1ap and 1bp. The connection structure further includes flat cables 7a, 7b and 7c for supplying a drive power and control signals from an 20 external control circuit.

However, in case where such a connection structure as shown in Figure 14 is adopted in a display panel of a larger size, particularly a liquid crystal display panel of an enlarged size as desired, 25 in recent years, the substrates 1ap and 1bp retain only narrow non-opposing peripheral areas while the input electrodes are increased in length, so that the

input electrodes are caused to have a higher impedance, thus being liable to cause a delay in transmission of drive waveforms to the display or pixel electrodes leading to pixels.

5 In order to obviate the difficulty, it may be conceived of lowering the impedance of the input electrodes by forming the electrodes in a larger thickness, but the realization thereof is difficult in view of the limitations from the production process
10 and size. Further, the increased impedance of the input electrodes is liable to cause a mal-function of data transfer during transmission of image data for a liquid crystal display panel of a higher definition to driver ICs.

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SUMMARY OF THE INVENTION

A generic of the present invention is to solve the above-mentioned problems of the prior art.

20 A more specific object of the present invention is to provide a circuit connection structure capable of providing a lower input electrode impedance while ensuring a minute connection pitch.

25 Another object of the present invention is to provide a display apparatus including such a circuit connection structure.

According to the present invention, there is provided a circuit connection structure, comprising: a

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first substrate having electrode terminals formed thereon, a semiconductor device having first electrodes and second electrodes with the first electrodes connected to the electrode terminals of the 5 first substrate, a flexible wiring member having thereon a pattern of conductors each extending from a first end to a second end on the flexible wiring member with the first ends of the conductors connected to the second electrodes of the semiconductor device, 10 and a circuit board having thereon electrode terminals connected to the second ends of the conductors on the flexible wiring member.

It is preferred that the first and second electrodes of the semiconductor device are used as 15 output electrodes and input electrodes, respectively, of the semiconductor device, so as to receive input data from the circuit board and supply output signals to the first substrate, thereby driving an electronic device including the first substrate.

20 The flexible wiring member may alternatively be constituted by a plurality of conductor wires each extending from a first end to a second end and not carried on a carrier film.

According to another aspect of the present 25 invention, there is provided a display apparatus, comprising:

a display panel comprising at least one

substrate having thereon pixel electrodes extending to form electrode terminals electrodes on a peripheral side of the substrate,

5 a semiconductor device having input electrodes, and output electrodes for supplying drive waveforms to the pixel electrodes of the display panel, and

10 a circuit board having electrode terminals for supplying an electric power and control signals to the semiconductor device; wherein

the electrode terminals on said at least one substrate of the display panel are connected to the output electrodes of the semiconductor device, and

15 the semiconductor device is connected to the circuit board via a flexible wiring member having thereon a pattern of conductors each extending from a first end to a second end so that the input electrodes of the semiconductor device are connected to the first ends of the conductors on the flexible wiring member, and the second ends of the conductors of the flexible wiring member are connected to the electrode terminals of the circuit board.

20 According to the circuit connection structure of the present invention, the first electrodes on one side of the semiconductor device may be connected to the electrode terminals on the first substrate which may carry pixel electrodes thereon via, e.g., an

anisotropic conductive adhesive (ACF), etc., and without via a flexible wiring member according to the TAB method, thereby ensuring a minute connection pitch. On the other hand, the second electrodes on 5 the other side of the semiconductor device are connected via conductors of the flexible wiring member to the electrode terminals of the circuit board. Particularly when the first and second electrodes of the semiconductor device are used as the output and 10 input electrodes, respectively, the semiconductor device can be supplied with an electric power and control signals at a low impedance from the circuit board through the flexible wiring member and the second electrodes, and can supply output signals 15 through the first electrodes at a minute arrangement pitch suitable for a high-definition output.

Particularly, if the circuit connection structure is included in a driver IC connection structure for a display apparatus including the first 20 substrate as a substrate carrying pixel electrodes of a display panel and the circuit board for supplying an electric power and control signals to the driver IC, the semiconductor device can be supplied with input data at a low impedance and without mal-function and 25 can supply drive signals to the display panel through the first electrodes arranged at a minute connection pitch suitable for a higher definition display.

These and other objects, features and advantages of the present invention will become more apparent upon a consideration of the following description of the preferred embodiments of the 5 present invention taken in conjunction with the accompanying drawings, wherein like parts are denoted by like reference numerals.

BRIEF DESCRIPTION OF THE DRAWINGS

10 Figure 1 is a plan view of a display apparatus including a drive circuit connection structure according to a first embodiment of the invention.

15. Figure 2 is a partial sectional view taken along a line A-A' in Figure 1.

Figures 3A - 3C are partial plan views for illustrating steps of bonding a driver IC onto a flexible wiring member in the display apparatus of Figures 1 and 2.

20 Figure 4 is a side sectional view of a resultant connection structure including the driver IC and the flexible wiring member connected to each other after the steps of Figures 3A - 3C.

25 Figures 5 - 6 and 8 - 10 are partial sectional views of display apparatus including drive circuit connection structures according to second to sixth embodiments, respectively, of the invention.

Figure 7 is a sectional view of a partial connection structure incorporated in the embodiment of Figure 8.

Figure 11 is a block diagram of a liquid 5 crystal display apparatus.

Figure 12 is a plan view of a liquid crystal display apparatus including a drive circuit connection structure.

Figure 13 is a partial sectional view taken 10 along a line A-A' in Figure 12.

Figure 14 is a partial sectional view of a liquid crystal display apparatus including another drive circuit connection structure.

15 DESCRIPTION OF THE PREFERRED EMBODIMENTS

Figure 1 is a plan view of a liquid crystal display apparatus, as an embodiment of display apparatus, including a drive circuit connection structure according to a first embodiment of the 20 present invention, and Figure 2 is a sectional view taken along a line A-A' in Figure 1. In Figures 1 and 2, reference numerals identical to those used in Figures 12 - 13 denote identical or like parts as in Figures 12 - 13.

25 Referring to Figures 1 and 2, a liquid crystal display apparatus 1 includes a pair of transparent substrates 1a and 1b of, e.g., glass, a

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polarizer 2 (which sandwiches the liquid crystal panel 1 together with a polarizer (not shown) on an opposite side), circuit boards 3 and 10 (of, e.g., a multi-layered glass epoxy PCB board) for supplying a drive power and control signals to driver ICs 5 and 9, flexible wiring members 4a and 8, flat cables 6 for supplying data signals to the circuit boards 3, and a flat cable 7 for supplying a drive power and control signals from an external control circuit (not shown).

5 Referring to Figure 2, a liquid crystal 11 (which is a ferroelectric liquid crystal in this embodiment but can also be a nematic liquid crystal, etc.) is disposed between the substrates 1a and 1b.

10 The substrates 1a and 1b are provided with electrodes for applying a drive voltage to the liquid crystal 1, and at least one thereof is provided with display electrodes or pixel electrodes leading to or defining the pixels and supplying display data signals to the respective pixels. The pixel electrodes extend

15 to non-opposing peripheries of the substrates 1a and/or the substrate 1b to form electrode terminals thereat. In this embodiment, both substrates 1a and 1b are provided with pixel electrodes so as to form a simple matrix electrode structure suitable for driving

20 the ferroelectric liquid crystal including, e.g., data electrodes on the substrate 1a and scanning electrodes on the substrate 1b, and the pixel electrodes are

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extended to non-opposing peripheries of both substrates 1a and 1b to form electrode terminals 12 thereat.

Each driver IC 5 is connected to electrode terminals 12 formed on the glass substrate 1b and extended to a peripheral side of the glass substrate 1b, and the input electrodes of the driver IC 5 are provided in advance with gold bumps 15 to which first ends of conductors on a flexible wiring member 4a are connected by the TAB method, and second (the other) ends of conductors on the flexible wiring member 4a are connected to electrode terminals of the circuit board 3.

At the time of assembling the display apparatus, each driver IC 5 is connected to the glass substrate 1b by first positionally aligning projection electrodes 13 (of, e.g., gold bumps formed on the output electrodes) of the device IC 5 with the electrode terminals 12 on the glass substrate 1b and connecting the projection electrodes 13 and the electrode terminals 12 via an anisotropic conductive adhesive 14 under application of heat and pressure. The projection electrodes 13 (of e.g., gold bumps) may be formed at a minute connection of preferably 50 μm or smaller as shown in Figures 3A - 3C described hereinafter.

By connecting the driver IC 5 provided with

the projection electrodes 13 to the electrode terminals 12 of the glass substrate 1b without via a flexible wiring member 4a, it becomes possible to obviate a thermal positional deviation due to heat 5 during the heat-pressure bonding, thus ensuring a prescribed connection pitch.

On the other hand, the second ends of conductors 17 (patterned copper foil of, e.g., 15 - 35 μm in thickness) on the flexible wiring member 4a 10 which have been connected in advance at their first ends to the input electrodes of the driver IC are connected to connection electrodes (electrode terminals) 19 of the circuit board 3 by heat-pressure bonding via an anisotropic conductive adhesive 18.

15 The copper foil electrodes 17 of the flexible wiring member 4a and the anisotropic conductive adhesive 18 respectively have prescribed thicknesses so that the conductors between the driver IC 5 and the circuit board 3 may have a lower impedance.

20 By supplying input signals to the driver IC 5 through low-impedance conductors 17 in the above-described manner, it becomes possible to obviate a delay in transmission of drive waveforms and a malfunction during data transmission. Incidentally, the 25 anisotropic conductive adhesive 14 for connecting the electrode terminals 12 on the glass substrate 1b and the output electrodes of the driver IC 5, and the

anisotropic conductive adhesive 18 for connecting the copper foil electrodes 17 on the flexible wiring member 4a and the connection electrodes 19 of the circuit board 3, may respectively be composed by 5 selecting electroconductive particles and an adhesive suitable therefor and need not be identical to each other.

More specifically, in the above-described embodiment, a commercially available anisotropic conductive film (ACF) may be used as the anisotropic conductive adhesive 18. Generally, however, the anisotropic conductive adhesive 18 may comprise a liquid insulating adhesive of heat-curable type or UV-curable type containing electroconductive particles dispersed therein. Alternatively it is also possible to use such a liquid insulating adhesive together with gold bumps formed on the electrode terminals. 15 Examples of the electroconductive particles may include Ni-plated or Ni-Au-plated resin particles of 2 - 5 μm in diameter for output electrode connection and Ni particles or Au-plated Ni particles of 5 - 10 μm in diameter for input electrode connection. 20

In the embodiment shown in Figure 1, the circuit connection structure characteristic to the 25 present invention as described above is applied to peripheral sides of only one substrate 1b of the display panel 1, and at a peripheral side of the other

substrate 1a, drivers IC 9 are connected via a TCP with respect to both input side and output side thereof similarly as in the case of Figure 12. However, it is also possible to adopt the circuit 5 connection structure having a sectional structure as shown in Figure 2 for bonding the driver ICs 9 to the substrate 1a similarly as the driver ICs 5 connected to the substrate 1b.

Then, a flexible wiring member 4a may be 10 connected to a driver IC 5 by the TAB method, for example, in the following manner.

First of all, as shown in Figure 3A, an aperture 24 is formed in a film carrier 4 of, e.g., polyimide or polyethylene terephthalate of ca. 25 - 15 125 μm in thickness, and tin-plated copper foil conductors 17 and 17a are formed thereon. Then, gold bumps 15 (Figure 2) formed on input electrodes of the driver IC 5 are positionally aligned with the copper foil patterns 17 and 17a and subjected to inner lead 20 bonding by means of a bonding tool. Instead of the above-mentioned tin plating of, e.g., 0.2 - 0.6 μm in thickness, it is also possible to use 0.2 - 10 μm -thick solder, 0.2 - 0.9 μm -thick gold or 0.2 - 10 μm -thick Ni for coating the copper foil conductors 17 and 25 17a.

The copper foil patterns 17a are used as support patterns for fixing the driver IC and

connected to dummy gold bumps (not shown) formed on the driver IC 5. However, it is also possible to dispose additional input electrodes there that can be connected to and receive signals from the flexible 5 wiring member 4a.

Then, as shown in Figure 3B, only the input side of the driver IC 4 is sealed with a resinous sealing agent 16. Then, an unnecessary portion of the flexible wiring member 4a is removed by punching to 10 leave a connection structure having a planar structure as shown in Figure 3C and a sectional structure as shown in Figure 4.

In this instance, the gold bumps (projecting electrodes) 13 on the output electrodes of the driver 15 IC may preferably be flattened by the bonding tool at the time of the inner lead bonding or by pressing with another flattening pressure member so as to provide a uniform projection height, in order to provide a reliable bonding between the electrode terminals 12 and the output electrodes 5 of the driver IC 4 with an 20 anisotropic conductive adhesive 14.

In a preferred example of circuit connection structure adopted for constituting a liquid crystal apparatus, each driver IC may have ca. 30 - 60 input 25 electrodes (second electrodes) arranged at a pitch of ca. 100 - 500 μm in both cases of constituting a data signal side IC and a scanning signal side IC.

Further, each driver IC may have ca. 200 - 500 output electrodes (first electrodes) arranged at a pitch of ca. 20 - 60 μm when used as a data signal side IC and at a pitch of ca. 100 - 300 μm when used as a scanning signal side IC. The circuit connection structure according to the present invention may be adopted for both data signal side ICs and scanning signal side IC but may preferably be used at least for data signal side ICs requiring output electrodes (first electrodes) arranged at a higher density in the embodiment of Figure 1.

Further to say, in a drive system using a liquid crystal showing bistability, such as a ferroelectric liquid crystal, an anti-ferroelectric liquid crystal or a BTN-mode liquid crystal driven in a binary mode, an areal gradational display mode according to a pixel division may be used, thus requiring an increased number of electrodes corresponding to the pixel division and arrangement of driver ICs and output electrodes at a higher density. In such cases, the circuit connection structure according to the present invention may preferably be used not only for data signal side ICs but also for scanning signal side ICs.

Figure 5 is a partial sectional view of a liquid crystal display apparatus including a drive circuit connection structure according to a second

embodiment of the present invention, wherein copper foil patterns 17 and connection electrodes 19 on a circuit board 3 are connected with a solder 20. Other members denoted by identical numerals as in Figure 2 5 represent identical or like members as in Figure 2, and 23 represents an aperture formed in a polyimide film carrier 4 at the soldering portion.

Figure 6 is a partial sectional view of a liquid crystal display apparatus including a drive 10 circuit connection structure according to a third embodiment of the present invention, wherein the connection structure is protected by a resinous sealing agent 21 and reinforced by a reinforcing plate 22. In this instance, after applying the resinous 15 sealing agent 21, the reinforcing plate may be bonded to the glass substrate 1a and the circuit board 3 from the back sides, so as to prevent the breakage of the electrical connection even when a stress is applied to the circuit board 3. It is particularly preferred to 20 adopt the reinforcement structure with the reinforcing plate 22 in case where one side of electrodes (output electrodes in this embodiment) of the driver IC 5 are bonded to electrode terminals on the substrate 1b without using a flexible wiring member as in this 25 embodiment.

Figure 7 is a sectional view a drive circuit connection structure according to a fourth embodiment

of the present invention, wherein a driver IC 5 is connected to a flexible wiring member 4a with an anisotropic conductive adhesive 26. The connection structure may be incorporated in a liquid crystal display apparatus having a sectional structure as shown in Figure 8, wherein the projecting electrodes 13 of the driver IC 5 are thermally pressure-bonded to electrode terminals 12 on the glass substrate 1b via an anisotropic conductive adhesive 14, and conductors 17 on the flexible wiring member 4a are thermally pressure-bonded to connection electrodes 19 on a circuit board 3.

In Figure 8, the conductors (copper foil patterns) 17 are disposed on an upper surface of the flexible wiring member 4a, and correspondingly the circuit board 3 is disposed above the flexible wiring member 4a (on the side having the conductors 17).

Figure 9 is a partial sectional view of a liquid crystal display apparatus including a drive circuit connection structure according to a fifth embodiment of the present invention, wherein a reinforcing plate 30 is disposed along and bonded to the circuit board 3, the driver IC 5 and another substrate 1a in a structure similar to the one shown in Figure 8. The resultant structure is resistant to a stress applied to the circuit board 3, etc., thus being able to avoid a breakage of the electrical

connection similarly as in the embodiment of Figure 6.

Figure 10 is a partial sectional view of a liquid crystal display apparatus including a drive circuit connection structure according to a sixth 5 embodiment of the present invention, wherein electrode terminals 12 on the glass substrate 1b and the projecting electrodes 13 on the driver IC 5 are thermally pressure-bonded to each other via an anisotropic conductive adhesive 14 after positional 10 alignment therebetween, input electrodes 29 of the driver IC 5 are electrically connected to connection electrodes on the circuit board 3 with conductive wires 28, and a reinforcing plate 30 is provided to fix the glass substrate 1a, the driver IC and the 15 circuit board 3 by bonding similarly as in Figure 9.

Finally, an organization of a liquid crystal display apparatus including a liquid crystal display panel as described above together with a control system thereof will be briefly described with 20 reference to a block diagram of such a liquid crystal display apparatus, for example, shown in Figure 11.

Referring to Figure 11, a liquid crystal display apparatus, such as a color display apparatus, may include a liquid crystal panel 1 as described 25 above according to the present invention, to which are connected a scanning signal application circuit 402 and a data signal application circuit 403 which are

sequentially connected to a canning signal control circuit 406 and a data signal control circuit 407, a drive control circuit 404 and then to a graphic controller 405. From the graphic controller 405, 5 video data and a scanning scheme signal are supplied to the scanning signal control circuit 406 and the data signal control circuit 407 via the drive control circuit 404.

The video data is converted into scanning 10 line address data and display data by the scanning signal control circuit 406 and the data signal control circuit 407, and the scanning scheme signal is supplied as it is to the data signal application circuit 402 and the data signal application circuit 15 403.

The scanning signal application circuit 402 applies a scanning signal determined by the scanning scheme signal to the scanning electrodes in a sequence determined by the scanning line address 20 data, and the data signal application circuit 403 applies data signals having waveforms determined by a combination of the display data determining white or black display states and the scanning scheme signal to the respective data electrodes. These data signals 25 and scanning signals are supplied via flat cables 6 and 7 to circuit board 3 and 10, whereby a picture display may be performed on the liquid crystal panel

1 as shown in Figure 1.

In the above, the circuit connection structure according to the present invention has been described principally as one suitably used in a liquid crystal display apparatus but may also be suitably incorporated in other display apparatus inclusive of those including self-light emission-type flat display panels as represented by an EL-display panel and a plasma display panel.

As described above, according to the present invention, by connecting electrode terminals disposed on a peripheral side of a display panel to first electrodes on one side of a drive semiconductor device with, e.g., an anisotropic conductive adhesive, the electrode terminals and the drive semiconductor device may be connected without a flexible wiring member, thus ensuring a small connection pitch.

On the other hand, second electrodes on the other side of the drive semiconductor device may be connected to a flexible wiring member, and the flexible wiring member is connected to a circuit board on a supply side with a solder or an anisotropic conductive adhesive, the power and signal can be supplied to the driver semiconductor device at a low impedance. As a result, even if a display panel, such as a liquid crystal display panel, is enlarged in areal size and driven at a higher speed, drive

waveforms can be transmitted to pixel electrodes of
the display panel without transmission delay or
deformation of drive waveforms. Further, in case of
supplying picture data for a display panel of a higher
5 definition it is possible to obviate a mal-function
during data transmission.

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WHAT IS CLAIMED IS:

1. A circuit connection structure, comprising: a first substrate having electrode terminals formed thereon, a semiconductor device having first 5 electrodes and second electrodes with the first electrodes connected to the electrode terminals of the first substrate, a flexible wiring member having thereon a pattern of conductors each extending from a first end to a second end on the flexible wiring member with the first ends of the conductors connected to the second electrodes of the semiconductor device, and a circuit board having thereon electrode terminals connected to the second ends of the conductors on the flexible wiring member.

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2. A connection structure according to Claim 1, wherein said semiconductor device has the first and second electrodes as output and input electrodes, respectively, thereof so as to receive input data from 20 the circuit board and supply output signals to the first substrate, thereby driving an electronic device including the first substrate.

3. A connection structure according to Claim 1, 25 wherein the second electrodes of the semiconductor device are connected to the first ends of the conductors on the flexible wiring member by a tape-

automated bonding method.

4. A connection structure according to Claim 1,
wherein the first electrodes of said semiconductor
5 device and the electrode terminals on the first
substrate are connected to each other substantially
solely with an anisotropic conductive adhesive.

5. A connection structure according to Claim 1,
10 wherein the second ends of the conductors on the
flexible wiring member and the electrode terminals on
the circuit board are connected to each other with a
solder.

15 6. A connection structure according to Claim 1,
wherein the second ends of the conductors on the
flexible wiring member and the electrode terminals on
the circuit board are connected to each other with an
anisotropic conductive adhesive.

20 7. A connection structure according to Claim 1,
wherein a connecting part between the second
electrodes of the semiconductor device and the first
ends of the conductors on the flexible wiring member
25 is sealed with a resin.

8. A connection structure according to Claim 1,

wherein the second electrodes of the semiconductor device are connected to the first ends of the conductors of the flexible wiring member with an anisotropic conductive adhesive.

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9. A connection structure according to Claim 1, further including a reinforcing plate fixedly supporting the first substrate and the circuit board.

10 10. A circuit connection structure, comprising: a
first substrate having electrode terminals formed
thereon, a semiconductor device having first
electrodes and second electrodes with the first
electrodes connected to the electrode terminals of the
first substrate, a flexible wiring member comprising a
plurality of conductor wires each extending from a
first end to a second end with the first ends of the
conductor wires connected to the second electrodes of
the semiconductor device, and a circuit board having
thereon electrode terminals connected to the second
ends of the conductor wires.

11. A connection structure according to Claim 10,
wherein said semiconductor device has the first and
25 second electrodes as output and input electrodes,
respectively, thereof so as to receive input data from
the circuit board and supply output signals to the

first substrate, thereby driving an electronic device including the first substrate.

12. A connection structure according to Claim 10,
5 further including a reinforcing plate fixedly supporting the first substrate and the circuit board.

13. A display apparatus, comprising:
a display panel comprising at least one
10 substrate having thereon pixel electrodes extending to form electrode terminals on a peripheral side of the substrate,
a semiconductor device having input electrodes, and output electrodes for supplying drive
15 waveforms to the pixel electrodes of the display panel, and
a circuit board having electrode terminals for supplying an electric power and control signals to the semiconductor device; wherein
20 the electrode terminals on said at least one substrate of the display panel are connected to the output electrodes of the semiconductor device, and
the semiconductor device is connected to the circuit board via a flexible wiring member having
25 thereon a pattern of conductors each extending from a first end to a second end so that the input electrodes of the semiconductor device are connected to the first

ends of the conductors on the flexible wiring member, and the second ends of the conductors of the flexible wiring member are connected to the electrode terminals of the circuit board.

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14. A connection structure according to Claim 13, wherein the second electrodes of the semiconductor device are connected to the first ends of the conductors on the flexible wiring member by a tape-
10 automated bonding method.

15. A display apparatus according to Claim 13, wherein the first electrodes of said semiconductor device and the electrode terminals on said one substrate of the display panel are connected to each other substantially solely with an anisotropic conductive adhesive.

16. A display apparatus according to Claim 13, 20 wherein the second ends of the conductors on the flexible wiring member and the electrode terminals on the circuit board are connected to each other with a solder.

25 17. A display apparatus according to Claim 13, wherein the second ends of the conductors on the flexible wiring member and the electrode terminals on

the circuit board are connected to each other with an anisotropic conductive adhesive.

18. A display apparatus according to Claim 13,
5 wherein a connecting part between the second electrodes of the semiconductor device and the first ends of the conductors on the flexible wiring member is sealed with a resin.

10 19. A display apparatus according to Claim 13, wherein the second electrodes of the semiconductor device are connected to the first ends of the conductors of the flexible wiring member with an anisotropic conductive adhesive.

15 20. A display apparatus according to Claim 13, further including a reinforcing plate fixedly supporting said at least one substrate and the circuit board.

20 21. A display apparatus according to Claim 20 wherein said reinforcing plate is bonded to and supports said one substrate and the circuit board from sides opposite to sides carrying the electrode terminals of said one substrate and the circuit board.

25 22. A display apparatus according to Claim 20,

wherein another substrate is disposed opposite to said one substrate from the display panel, and said reinforcing plate is bonded to and supports said another substrate from its side not facing said one 5 substrate and said circuit board from its side opposite to the side carrying the electrode terminals.

23. A display apparatus according to Claim 13, wherein said display panel is a liquid crystal display 10 panel.

24. A display apparatus, comprising:
a display panel comprising at least one substrate having thereon pixel electrodes extending to 15 form electrode terminals on a peripheral side of the substrate,
a semiconductor device having input electrodes, and output electrodes for supplying drive waveforms to the pixel electrodes of the display 20 panel, and

a circuit board having electrode terminals for supplying an electric power and control signals to the semiconductor device; wherein
the electrode terminals on said at least one 25 substrate of the display panel are connected to the output electrodes of the semiconductor device, and
the semiconductor device is connected to the

circuit board via a flexible wiring member comprising a plurality of conductor wires each extending from a first end to a second end so that the input electrodes of the semiconductor device are connected to the first 5 ends of the conductor wires of the flexible wiring member, and the second ends of the conductor wires of the flexible wiring member are connected to the electrode terminals of the circuit board.

10 25. A display apparatus according to Claim 24, further including a reinforcing plate fixedly supporting said at least one substrate and the circuit board.

15 26. A display apparatus according to Claim 24, wherein said display panel is a liquid crystal display panel.

20 27. A tape carrier package structure comprising a semiconductor device having first electrodes arranged data pitch of 20 - 60 μm , and a flexible wiring member comprising a flexible carrier film and a pattern of conductors formed on the carrier film, each conductor on the carrier film extending from a first end to a 25 second end, the first ends of the conductors being connected to the second electrodes of the semiconductor device.

28. A structure according to Claim 27, wherein
said semiconductor device has the first and second
electrodes as output and input electrodes,
respectively, thereof.

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29. A structure according to Claim 27, wherein
the second electrodes of the semiconductor device are
connected to the first ends of the conductors on the
flexible wiring member by a tape-automated bonding
10 method.

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ABSTRACT OF THE DISCLOSURE

A circuit connection structure is formed by a first substrate having electrode terminals formed thereon, a semiconductor device having first 5 electrodes and second electrodes with the first electrodes connected to the electrode terminals of the first substrate, a flexible wiring member having thereon a pattern of conductors each extending from a first end to a second end on the flexible wiring member with the first ends of the conductors connected to the second electrodes of the semiconductor device, and a circuit board having thereon electrode terminals connected to the second ends of the conductors on the flexible wiring member. The circuit connection 10 structure may suitably be incorporated in a display apparatus including a display panel having the first substrate for carrying pixel electrodes and allows a small pitch desired for a high definition display by the panel while ensuring a low-impedance power and 15 signal supply to the semiconductor device.

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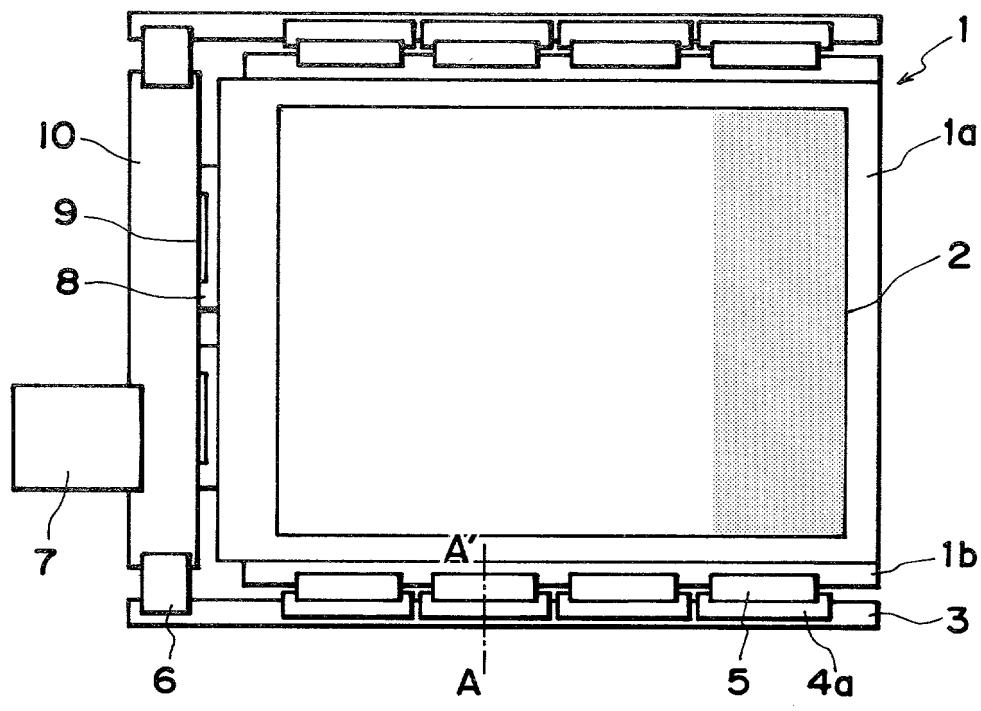


FIG. 1

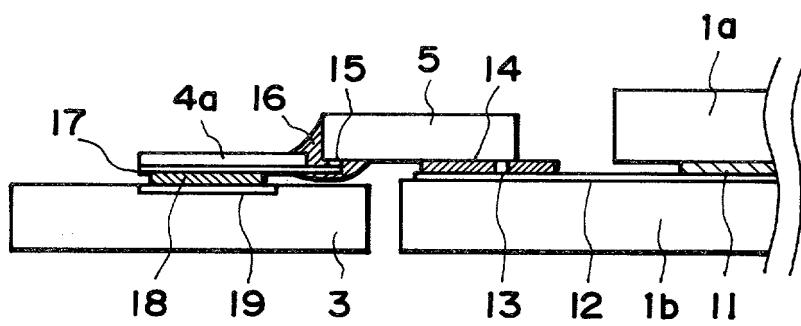


FIG. 2

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FIG. 3A

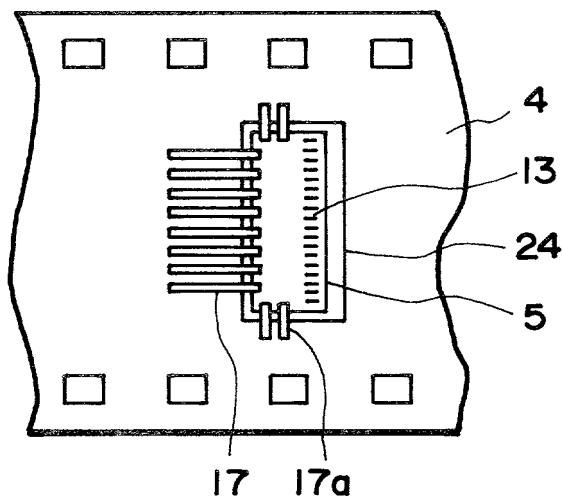


FIG. 3B

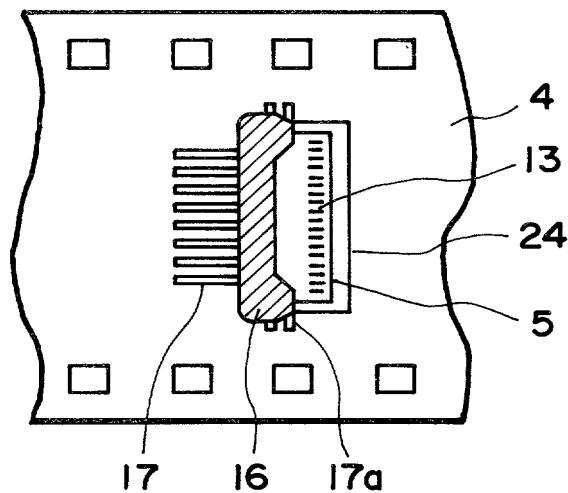
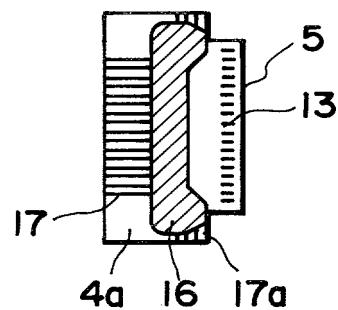


FIG. 3C



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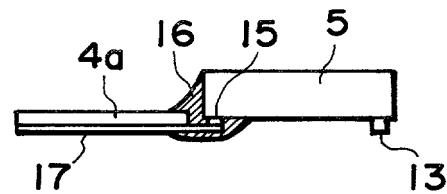


FIG. 4

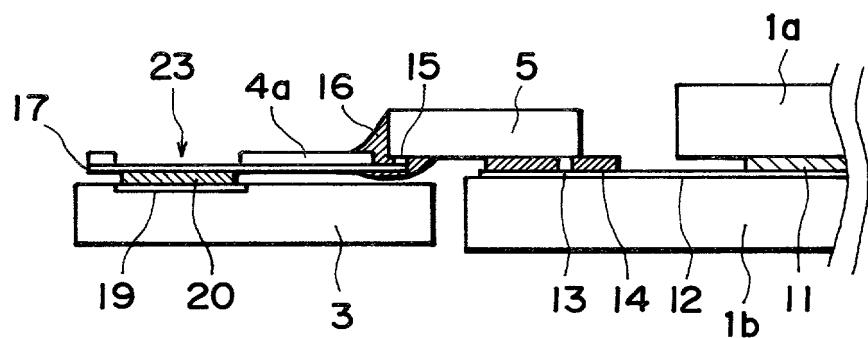


FIG. 5

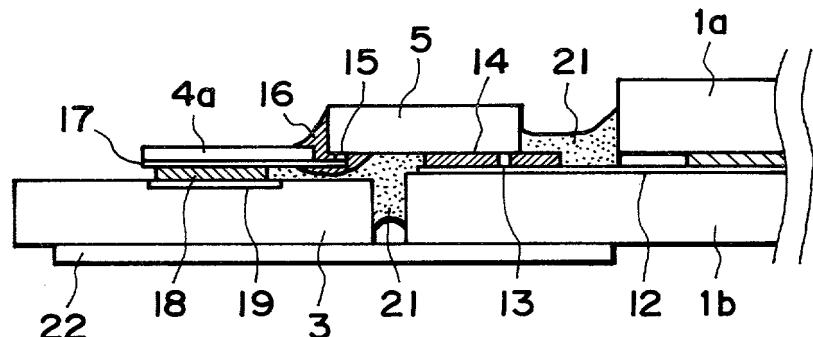


FIG. 6

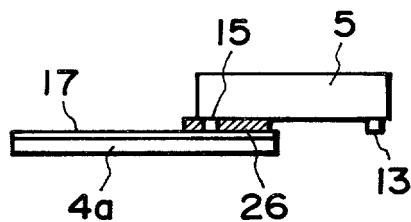


FIG. 7

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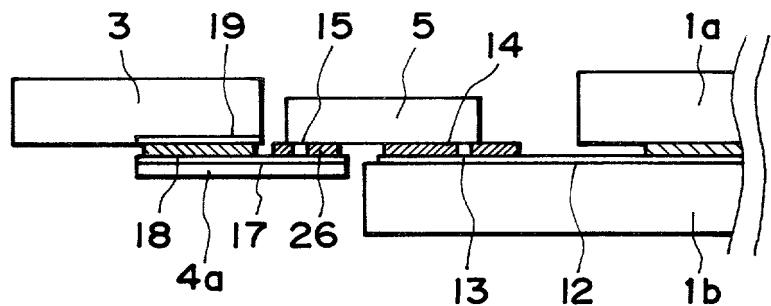


FIG. 8

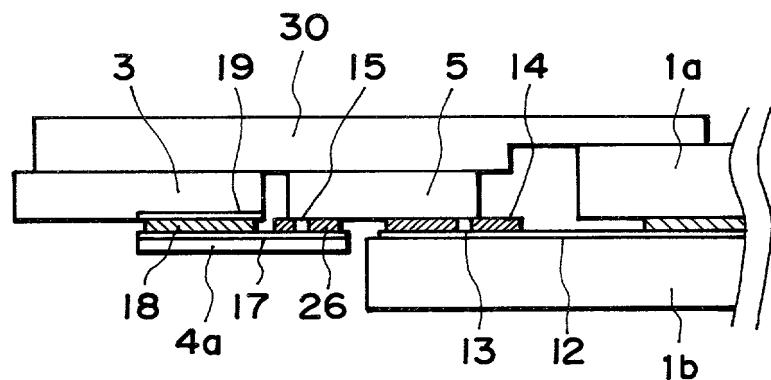


FIG. 9

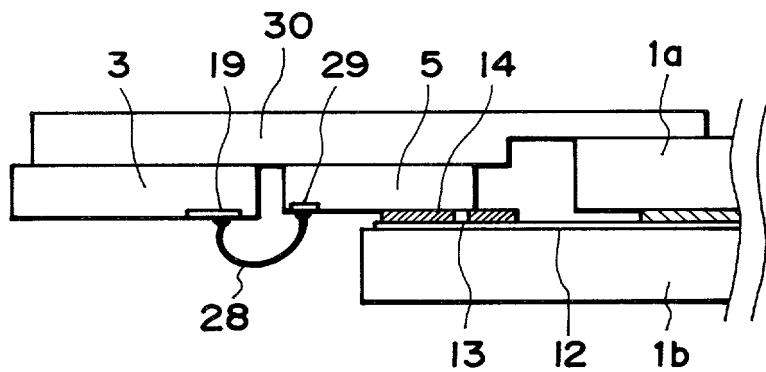


FIG. 10

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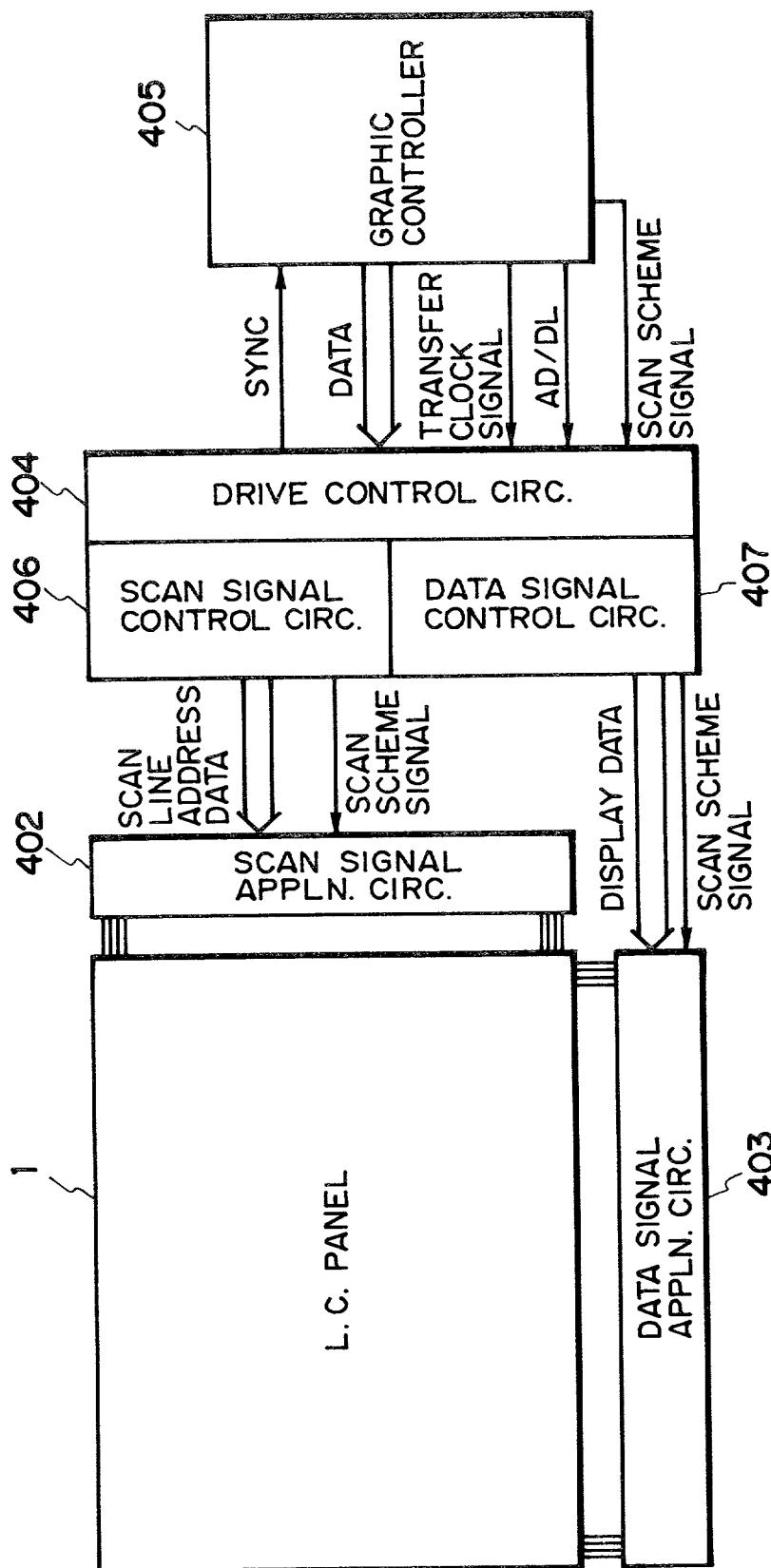


FIG. 11

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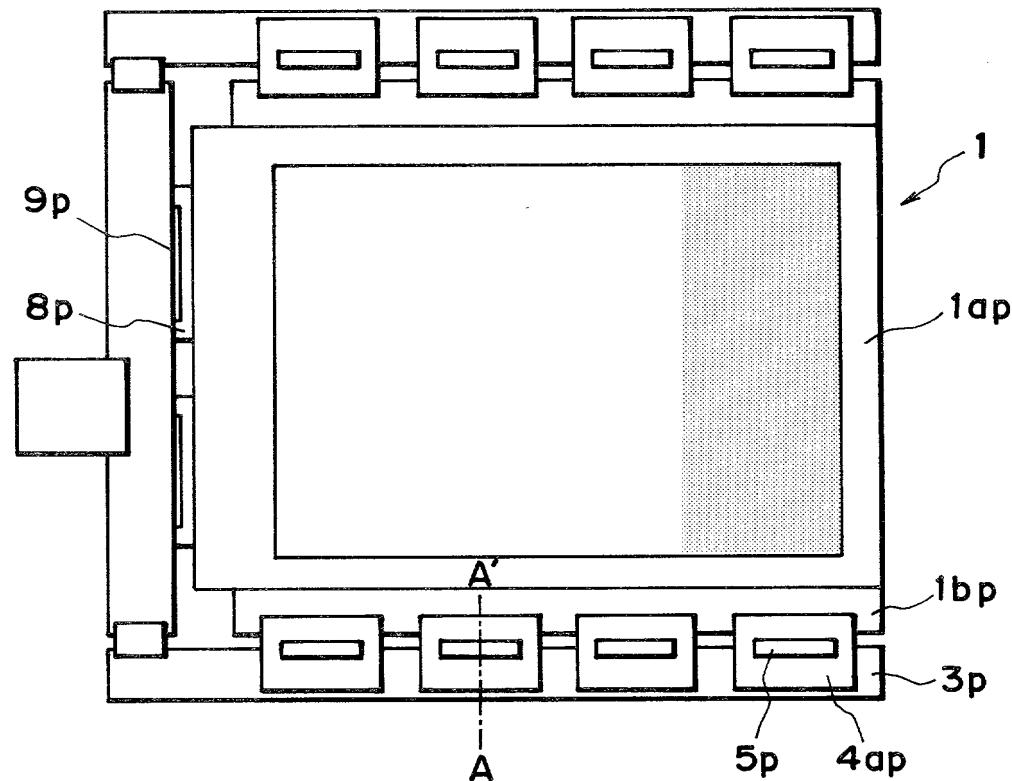


FIG. 12

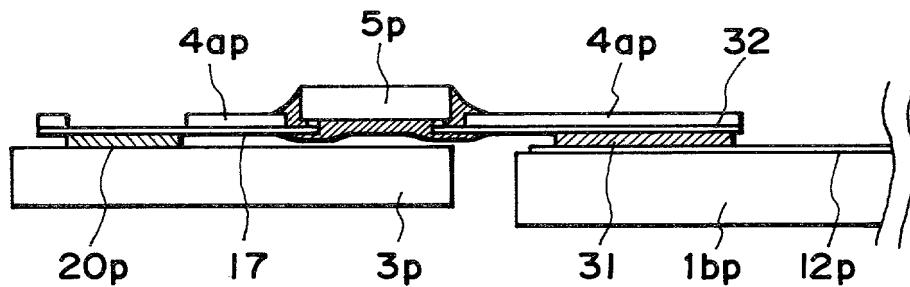


FIG. 13

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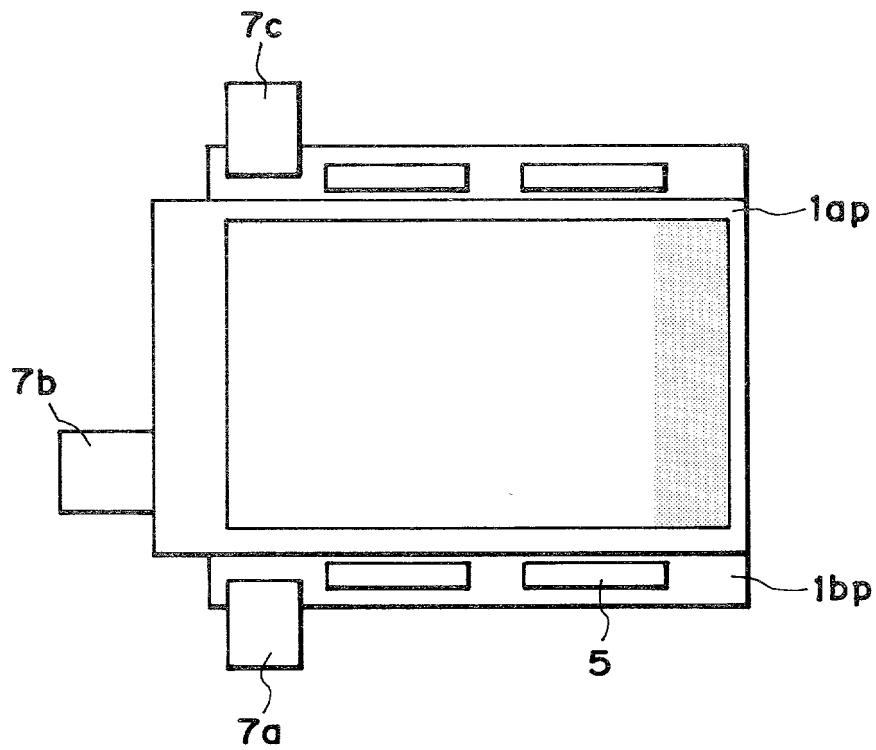


FIG. 14

**COMBINED DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION**

70673

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;
I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a

patent is sought in the invention entitled DRIVE CIRCUIT CONNECTION STRUCTURE AND
DISPLAY APPARATUS INCLUDING THE CONNECTION STRUCTURE

, the specification of which

is attached hereto. was filed on 10/MAR/1997 as United States Appl'n No. 08/814,082

and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

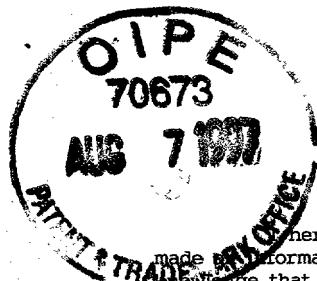
<u>Country</u>	<u>Application No.</u>	<u>Filed(Day/Mo./Yr.)</u>	<u>Priority Claimed (Yes/No)</u>
Japan	059665/1996(Pat.)	15/MAR/1996	Yes

I hereby appoint Joseph M. Fitzpatrick (Registration No. 17,398), Lawrence F. Scinto (Registration No. 18,973), William J. Brunet (Registration No. 20,452), Robert L. Baechtold (Registration No. 20,860), John A. O'Brien (Registration No. 24,367), Neils T. Lippert (Registration No. 25,888), John A. Krause (Registration No. 24,613), Henry J. Renk (Registration No. 25,499), Peter Saxon (Registration No. 24,947), Anthony M. Zupcic (Registration No. 27,276), Charles P. Baker (Registration No. 26,702), Stevan J. Bosses (Registration No. 22,291), Edward E. Vassallo (Registration No. 29,117), Ronald A. Clayton (Registration No. 26,718), Lawrence A. Stahl (Registration No. 30,110), Laura A. Bauer (Registration No. 29,767), Leonard P. Diana (Registration No. 29,296), David M. Quinlan (Registration No. 26,641), Nicholas N. Kallas (Registration No. 31,530), William M. Wannisky (Registration No. 28,373), Lawrence Alaburda (Registration No. 31,583), Lawrence S. Perry (Registration No. 31,865), Robert H. Fischer (Registration No. 30,051), Christopher Philip Wrist (Registration No. 32,078), Gary M. Jacobs (Registration No. 28,861), Michael K. O'Neill (Registration No. 32,622), Bruce C. Haas (Registration No. 32,734), Scott K. Reed (Registration No. 32,433), Scott D. Malpede (Registration No. 32,533), John A. Mitchell (Registration No. 19,032), Fredrick M. Zulow (Registration No. 32,452), Richard P. Bauer (Registration No. 31,588), Eric B. Janofsky (Registration No. 30,759), Warren E. Olsen (Registration No. 27,290), Abigail F. Cousins (Registration No. 29,292), Alan W. Fiedler (Registration No. 33,690), Jennifer A. Tegfeldt (Registration No. 31,310), Steven E. Warner (Registration No. 33,326), Thomas J. O'Connell (Registration No. 33,202), Aaron C. Deditch (Registration No. 33,865), Penina Wollman (Registration No. 30,816), David L. Schaeffer (Registration No. 32,716), Jack S. Cubert (Registration No. 24,245), Mark A. Williamson (Registration No. 33,628), John T. Whelan (Registration No. 32,448), Patricia M. Drost (Registration No. 29,790), Jean K. Dudek (Registration No. 30,938), Raymond R. Mandra (Registration No. 34,382) and Dominick A. Conde (Registration No. 33,856), my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Address all correspondence to:

FITZPATRICK, CELLA, HARPER & SCINTO

277 Park Avenue
New York, N.Y. 10172
Telephone No. (212)758-2400



**COMBINED DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION**

(Page 2)

hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that Such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of First Inventor

Masanori TAKAHASHI

Inventor's signature

Masanori Takahashi

Date July 18, 1997 Citizen/Subject of JAPAN

Residence 2-6-44-101 Tomoe, Chigasaki-shi, Kanagawa-ken, Japan

Post Office Address c/o CANON KABUSHIKI KAISHA

3-30-2 Shimomaruko, Ohta-ku, Tokyo, Japan

Full name of Second Inventor, if any Riichi SAITO

Inventor's signature Riichi Saito

Date July 22, 1997 Citizen/Subject of JAPAN

Residence 34-2-610 Fujisawa, Fujisawa-shi, Kanagawa-ken, Japan

Post Office Address c/o CANON KABUSHIKI KAISHA

3-30-2 Shimomaruko, Ohta-ku, Tokyo, Japan

Full name of Third Inventor, if any Toshimichi OUCHI

Inventor's signature Toshimichi Ouchi

Date July 18, 1997 Citizen/Subject of JAPAN

Residence 740-29-306 Kudencho, Sakae-ku, Yokohama-shi, Kanagawa-ken, Japan

Post Office Address c/o CANON KABUSHIKI KAISHA

3-30-2 Shimomaruko, Ohta-ku, Tokyo, Japan

Full name of Fourth Inventor, if any

Inventor's signature

Date _____ Citizen/Subject of _____

Residence _____

Post Office Address _____

Full name of Fifth Inventor, if any

Inventor's signature

Date _____ Citizen/Subject of _____

Residence _____

Post Office Address _____

Full name of Sixth Inventor, if any

Inventor's signature

Date _____ Citizen/Subject of _____

Residence _____

Post Office Address _____